imall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

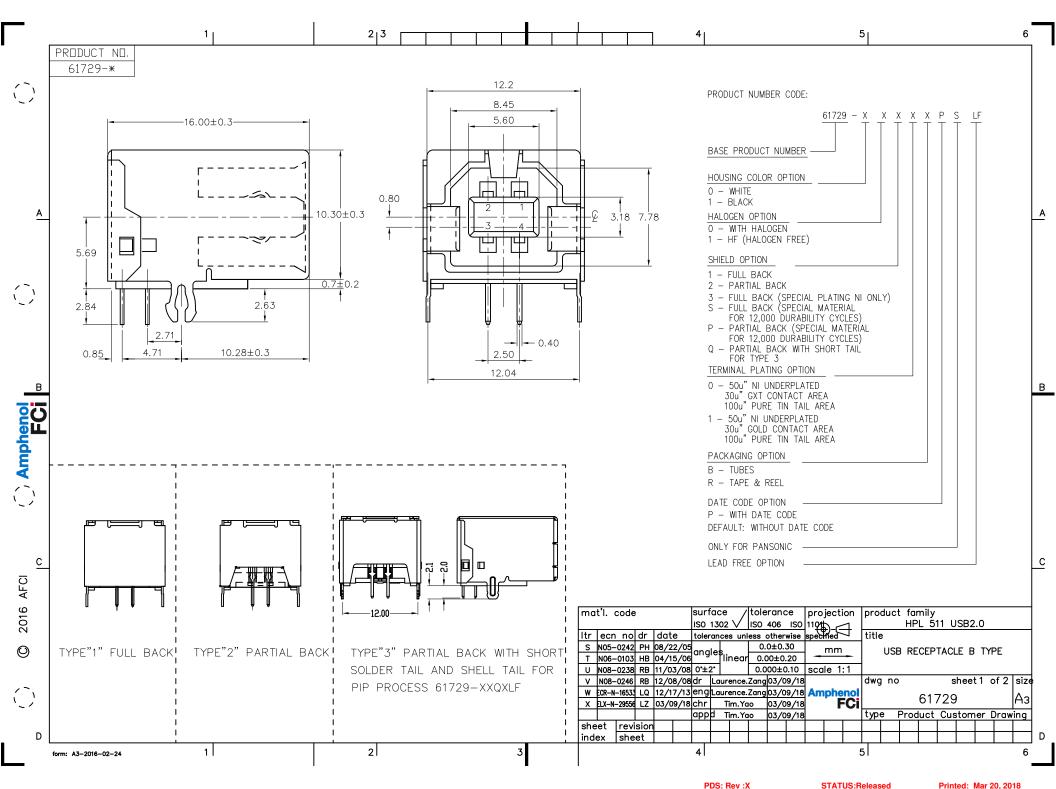
We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832 Email & Skype: info@chipsmall.com Web: www.chipsmall.com Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





 $A = \begin{pmatrix} 0.92\pm0.08 \\ \hline 0.08(2X) \\ \hline 0.08(2X) \\ \hline 0.08(2X) \\ \hline 12.04\pm0.05 \\ \hline Y \end{bmatrix}$

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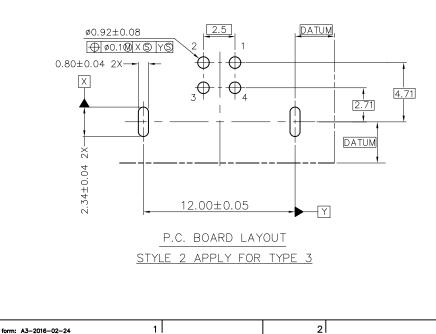
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P.C. BOARD LAYOUT STYLE 1 APPLY FOR TYPE 1 & 2



NOTES:

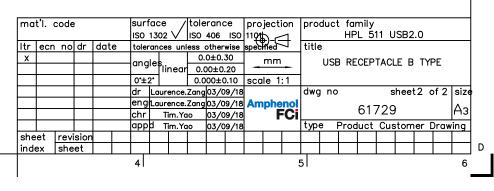
1. MATERIAL:

SHIELD & CONTACTS: COPPER ALLOY HOUSING: UL 94V-0 ,HIGHT TEMPERATURE THERMOPLASTIC. COLOR: SEE PRODUCT NUMBER CODE.

- 2. PLATING: SEE PRODUCT NUMBER CODE.
 - SHIELD: BRIGHT TIN, NICKEL UNDERPLATE(USED FOR WAVE SOLDER PROCESS), PLATING NICKEL ONLY(USED FOR PIP PROCESS).

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- 3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
- 4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)
- 5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
- 6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
- 7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TERMERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.
- 8. THE PART CAN BE USED FOR PIP PROCESS.



STATUS:Released

PDS: Rev :X

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